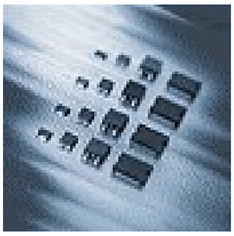

Material Content Data Sheet

RoHS Halogen-Free

Sales Product Name	BCR 10PN H6327	**Issued**	29. August 2013
MA#	MA001094638		
Package	PG-SOT363-6-1	**Weight***	6.29 mg

Construction Element	**Material Group**	**Substances**	**CAS# if applicable**	**Weight [mg]**	**Average Mass [%]**	**Sum [%]**	**Average Mass [ppm]**	**Sum [ppm]**
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		24	
	noble metal	gold	7440-57-5	0.015	0.24		2392	
	inorganic material	silicon	7440-21-3	0.073	1.17	1.41	11673	14089
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		458	
	non noble metal	chromium	7440-47-3	0.009	0.14		1375	
	non noble metal	copper	7440-50-8	2.869	45.66	45.86	456473	458398
wire	non noble metal	copper	7440-50-8	0.010	0.16	0.16	1633	1633
encapsulation	organic material	carbon black	1333-86-4	0.030	0.48		4830	
	plastics	epoxy resin	-	0.653	10.38		103848	
	inorganic material	silicondioxide	60676-86-0	2.353	37.43	48.29	374335	483013
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33924	33924
plating	noble metal	silver	7440-22-4	0.056	0.89	0.89	8943	8943
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com